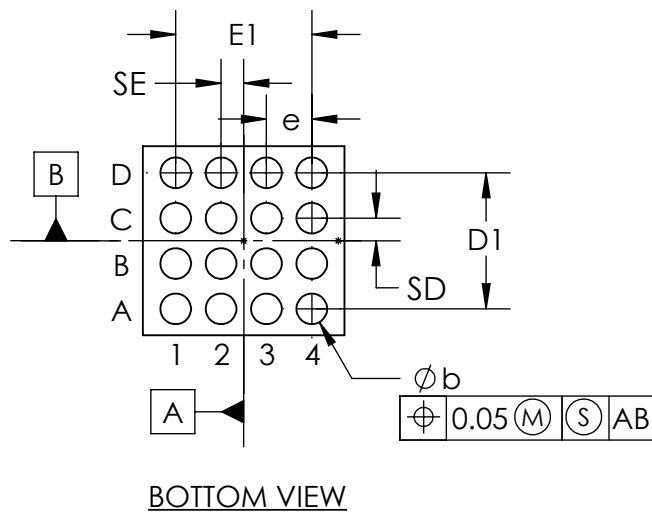
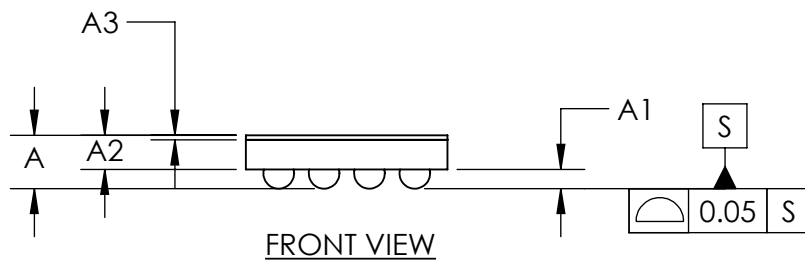
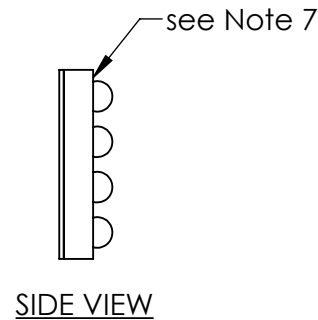
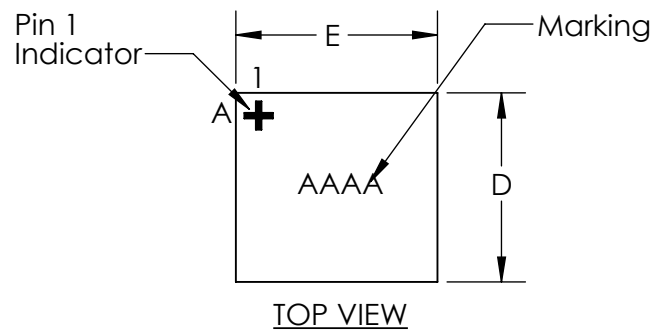


DOCUMENT TYPE: POD
DOCUMENT ID #: 21-100454
REVISION: D-000
DOCUMENT TITLE: PACKAGE OUTLINE 16 BUMPS THIN WLP PKG. 0
EFFECTIVE DATE: 04/17/2024
EXPIRATION DATE:
CHANGE NUMBER: 1207797
ORIGINATOR: Josie Hoylar

REASON FOR CHANGE:
Change A value from 0.50 MAX to 0.47 +/-0.03



COMMON DIMENSIONS	
A	0.47 ±0.03
A1	0.19 ±0.03
A2	0.28 REF
A3	0.040* BASIC
b	∅0.27 ±0.03
D	1.668 ±0.025
E	1.778 ±0.025
D1	1.20 BASIC
E1	1.20 BASIC
e	0.40 BASIC
SD	0.20 BASIC
SE	0.20 BASIC
DEPOPULATED BUMPS: NONE	

NOTES:

1. Terminal pitch is defined by terminal center to center value.
2. Outer dimension is defined by center lines between scribe lines.
3. All dimensions in millimeter.
4. Marking shown is for package orientation reference only.
5. Tolerance is ± 0.02 unless specified otherwise.
6. All dimensions apply to PbFree (+) package codes only.
7. Front - side finish can be either Black or Clear.
8. *For 12" wafer, A3 = 0.025mm.



TITLE PACKAGE OUTLINE 16 BUMPS
THIN WLP PKG. 0.4 mm PITCH, N161B1+1

APPROVAL	DOCUMENT CONTROL NO. 21-100454	REV. D	1/1
----------	-----------------------------------	-----------	-----

REVISION HISTORY

REV	CHANGES MADE	DATE	INIT.
A	CN 1071182. Initial Release.	11/04/19	RG
B	CN 1077736. Change D from 1.628 to 1.668, Change E from 1.628 to 1.778	02/02/20	SJT
C	CN 1091859. Add Note 8, A3 value for 12in wafer	07/07/20	SJT
D	CN 1207797. Change A value from 0.50 MAX to 0.47 +/-0.03	04/17/24	JH

TITLE: PACKAGE OUTLINE 16 BUMPS THIN WLP PKG. 0.4 mm PITCH, N161B1+1

DOCUMENT I.D.
21-100454

REVISION
D

PAGE
2

